

Electrical Characteristics

Type Number	DC Spark-Over Voltage	Min. Insulation Resistance		Max. Capacitance (1kHz-6Vmax.)	Surge Current Capacity	Surge Life Test
	Vs	Test Voltage	I _R	C _j	8/20μs	
	V	V	MΩ	pF	A	
RL501-141N	140(126~210)	50	100	1	500	1kHz-10KV Max
RL501-201M	200±20%	100	100	1	500	1kHz-10KV Max
RL501-301M	300±20%	100	100	1	500	1kHz-10KV Max
RL501-401M	400±20%	250	100	1	500	1kHz-10KV Max
RL501-501M	500±20%	250	100	1	500	1kHz-10KV Max
RL501-601M	600±20%	250	100	1	500	1kHz-10KV Max
RL501-102M	1000±20%	500	100	1	500	1kHz-10KV Max

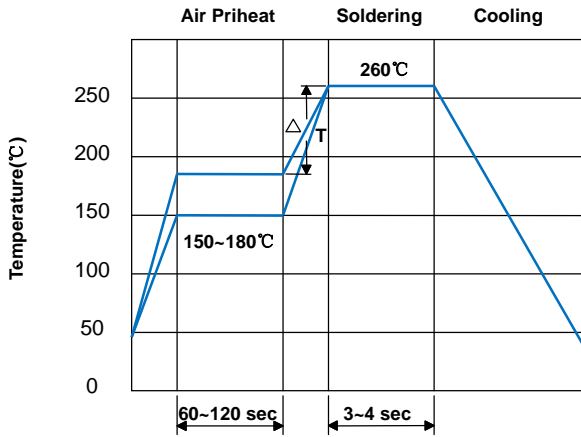
Test Methods And Results

Test Item	Test Method	Specification
DC Spark-over Voltage Vs(V)	Add and measure the DC Voltage gradually Maxto get the discharge threshold voltage. The measuring current is 1mA/1 second max.	It depends on each spec.
Insulation Resistance	Measure the insulation resistance of two end of leadwire under the specified DC voltage.	100MΩ min.
Capacitance C _j (pF)	Measure the Electrostatic Capacitance under the test condition of 1KHz,DC 6V(max).	1pF max.
Life(JSE)	Apply 10 KV voltage charged in 1500pF condenser and apply the current to the specimen,200 times at 10 seconds of intervals	Insulation Resistance & Capacitance to meet the specified value. Appearance: No cracks or failures.
Cold Resistance	Measurement after -40℃ /1000 HRS & normal temperature/2 HRS.	Features are conformed to rated spec.
Heat Resistance	Measurement after 125℃ /1000 HRS & normal temperature/2 HRS.	
Humidity Resistance	Measurement after humidity 90~95 ℃ (45 ℃)/1000 HRS & normal temperature/2 HRS.	
Temperature Cycle	10 times repetition of cycle -40 ℃ /30min →normal, temp/2 min →125℃ /30min, measurement after normal temp/2 HRS.	
Pull Strength	Apply 0.5kg load for 10sec.	Lead shall not pull out to snap.
Flexural Strength	Bend lead wire at the point of 2mm from body under 0.25 load and back to its original point. Repeat 1 time.	



Recommended Soldering Conditions

Flow Soldering Conditions



Hand Soldering

Solder iron temperature: $350 \pm 5^\circ\text{C}$
Heating time: 3 seconds max.

General attention to soldering

- 1.High soldering temperatures and long soldering times can cause leaching of the termination, decrease in adherence strength, and the change of characteristic may occur.
- 2.For soldering, please refer to the soldering curves above. However, please keep exposures to temperatures exceeding 200°C to fewer than 50 seconds.
- 3.Please use a mild flux (containing less than 0.2wt% Cl). Also, if the flux is water soluble, be sure to wash thoroughly to remove any residue from the underside of components that could affect resistance.

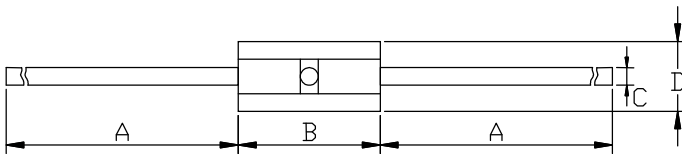
- 1) Time shown in the above figures is measured from the point when chip surface reaches temperature.
- 2) Temperature difference in high temperature part should be within 110°C
- 3) After soldering, do not force cool, allow the parts to cool gradually.

Cleaning

When using ultrasonic cleaning, the board may resonate if the output power is too high. Since this vibration can cause cracking or a decrease in the adherence of the termination, we recommend that you use the conditions below.

Frequency: 40kHz max.
Output power: 20W/liter
Cleaning time: 5 minutes max.

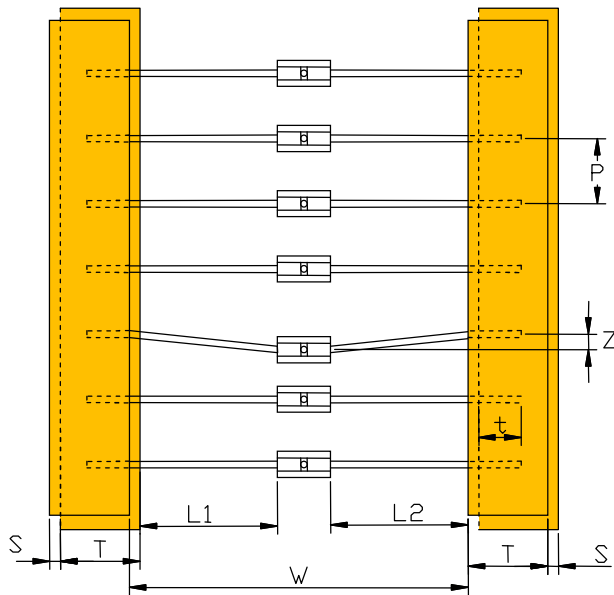
Dimensions



DIM	Millimeters	Inches
A	28±3.0	1.102±0.118
B	4.0±0.3	0.157±0.012
C	0.5±0.05	0.02±0.002
D	Φ2.0±0.3	0.079±0.012



Packaging Information



Symbol	Millimeters	Inches
W	52.0±2.0	2.047±0.079
P	5.0±0.5	0.197±0.02
L1-L2	1.0 max	0.039max
T	6.0±1.0	0.236±0.039
Z	1.2max	0.047max
t	3.2max	0.126max
S	0.8max	0.031max
A	75.0	2.953
B	68.0	2.677
C	255.0	10.039
Quantity:3000PCS / inner box		

